HEAT SINK COMPOUND

Description:

High electronic heat dissipating ointment is a kind of metal oxide, which contains dielectric heat body and is widely used in the electronics and electrical production industry. It is usually used as the heat transfer body between the heating parts in the assembly of products. Use of temperature: $-20^{\circ} C^{2}200^{\circ}$

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Purpose :

- The heating part of the electronic component is also used the radiator contact.

Products Code	Packings	Capacity	
I100279-4L	Can	4L	
I100279-18L	Pail	18L	
I100279-200L	Durm	200L	

Performance characteristics :

- Stability of chemical properties
- Excellent thermal conductivity

Typical physical properties:

HEAT SINK COMPOUND	NLGI	Coning 1/4	Drop point ℃	Appearance
	1~2	64 [~] 85	<180	White opaque semid

Matters needing attention:

- 1. Please use it in a suitable temperature range, so as not to cause the grease to freeze or melt.
- 2. Sealed storage.

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